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Intel Legal Team

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Page 1 of 11 including cover

Urgent

Confidential

Date: October 21, 2005

To: Examiner: *David E. Graybill*      Fax: (571) 273 8300      Art Unit: 2822  
USPTO

From: *Laleh Jalali*      Fax: 703-759 0243      M/S:

Subject: *Microelectronic Die Providing Improved Heat Dissipation and Method of Packaging Same*

Serial No. *10/073,859*

Inventor: *Crippen*

Filed: *February 14, 2002*      Docket No. *P12659*

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I hereby certify that the below listed correspondence is being facsimile transmitted to the USPTO to: Commissioner for Patents, Washington DC 20231 on October 21, 2005.

Date: October 21, 2005

  
Laleh Jalali

**Included in this transmission:**

Fax Cover Sheet (1 page)

Response to Non Compliant Amendment (10 pages)

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Attorney Docket P12659  
Serial No. 10/073,859  
Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

|                              |   |                             |
|------------------------------|---|-----------------------------|
| In re Patent Application of: | ) |                             |
|                              | ) |                             |
| Warren Stuart CRIPPEN        | ) | Examiner: David E. Graybill |
|                              | ) |                             |
| Application No. 10/073,859   | ) | Art Unit: 2822              |
|                              | ) |                             |
| Filed: February 14, 2002     | ) |                             |
|                              | ) |                             |
| For: Microelectronic Die     | ) |                             |
| Providing Improved Heat      | ) |                             |
| Dissipation and Method       | ) |                             |
| Of Packaging Same            | ) |                             |

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

**Response to Notice of Non-Compliant Amendment**

In response to the Notice of Non-Compliant Amendment of September 21, 2005, the instant Response is being submitted, and includes the entire "Amendments to the Specification" section of Applicant's Amendment of May 16, 2005 in corrected format.